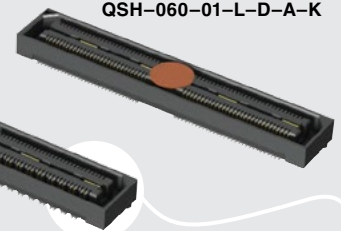


QSH-060-01-L-D-DP-A

QSH-060-01-L-D-A-K



QSH-030-01-F-D-A



(0.50 mm) .0197"

QSH SERIES

HIGH-SPEED GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QSH

Insulator Material: Liquid Crystal Polymer

Contact Material: Phosphor Bronze

Plating: Au or Sn over 50 μ" (1.27 μm) Ni

Current Rating: Contact:

2 A per pin (2 pins powered)

Ground Plane: 25 A per ground plane (1 ground plane powered)

Operating Temp Range: -55 °C to +125 °C

Voltage Rating: 175 VAC (5 mm Stack Height)

Max Cycles: 100

RoHS Compliant: Yes

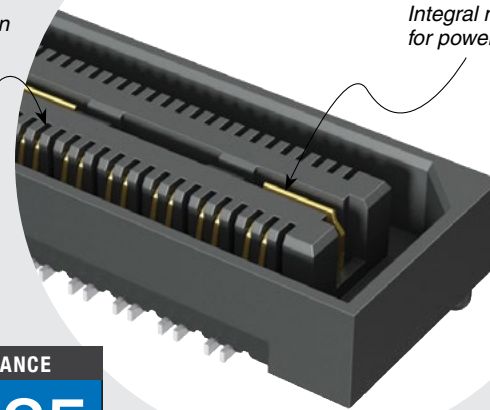
Board Mates: QTH

Cable Mates: HQCD, HQDP (See Also Available Note)

Standoffs: SO

Blade & Beam Design

Integral metal plane for power or ground



POWER/SIGNAL APPLICATION



Compatible with UMP/TUMPS for flexible two-piece power/signal solutions

HIGH-SPEED CHANNEL PERFORMANCE

QTH/QSH @ 5 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

25 Gbps

PROCESSING

Lead-Free Solderable: Yes

SMT Lead Coplanarity: (0.10 mm) .004" max (020-060)

Board Stacking: For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



PROTOCOLS

- 100 GbE
- Hypertransport™
- XAUI
- PCI Express®
- InfiniBand™

ALSO AVAILABLE (MOQ Required)

- 15 mm, 22 mm and 30 mm stack height
- 30 μ" (0.76 μm) Gold (Specify -H plating for Data Rate cable mating applications.)
- Edge Mount & Guide Posts
- 80 (-DP), 120, 150 positions per row
- Retention Option

Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.



—030, —060, —090
(60 total pins per bank = -D)

—020, —040, —060
(20 pairs per bank = -D-DP)

—F

= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

—L

= 10 μ" (0.25 μm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

—C*

= Electro-Polished Selective
50 μ" (1.27 μm) min Au over 150 μ" (3.81 μm) Ni on Signal Pins in contact area, 10 μ" (0.25 μm) min Au over 50 μ" (1.27 μm) Ni on Ground Plane in contact area, Matte Tin over 50 μ" (1.27 μm) min Ni on all solder tails

—D

= Single-Ended

—D-DP

= Differential Pair (-01 only)

—K

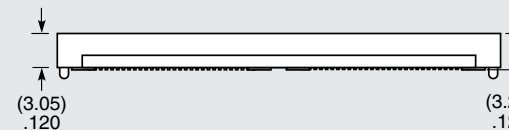
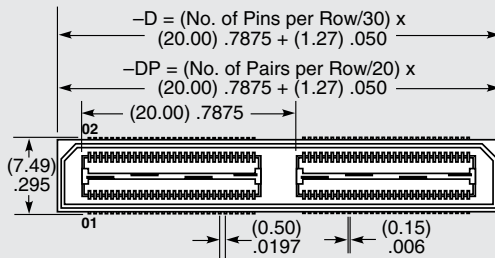
= (8.25 mm) .325" DIA Polyimide Film Pick & Place Pad

—TR

= Tape & Reel (-090 positions maximum)

—L

= Latching Option (Not available on -060 (-D-DP) & -090 positions)



*Note: -C Plating passes 10 year MFG testing

QTH LEAD STYLE	MATED HEIGHT WITH QSH*
-01	(5.00) .197
-02	(8.00) .315
-03	(11.00) .433
-04	(16.00) .630
-05	(19.00) .748
-07	(25.00) .984
-09	(14.00) .551

*Processing conditions will affect mated height. See SO Series for board space tolerances